

**COPY****Amendments to the Specification:**

Please replace the paragraph beginning at page 1, line 3, with the following rewritten paragraph:

--This application is a continuation application of U.S. Patent Application No. 10/208,381, filed July 29, 2002, which is a divisional of U.S. Patent Application No. 09/792,488, filed February 23, 2001, now U.S. Patent No. 6,454,924, which claims the benefit of U.S. provisional patent application nos. 60/184,381 filed February 23, 2000 and 60/225,999 filed August 16, 2000. This application is ~~also being filed on the same day as~~ related to U.S. non-provisional application no. 09/792,335 \_\_\_\_\_ entitled "Chips With Elevated Sample Surfaces" by Pierre F. Indermuhle et al. (~~Attorney Docket No. 020144-000810~~). All of the above provisional and non-provisional patent applications are herein incorporated by reference in their entirety for all purposes and are all assigned to the same assignee as the present application. - --

Please replace the paragraph beginning at page 30, line 5 with the following paragraph:

-- Additional details regarding dispenser assemblies and sample chips can be found in U.S. non-provisional application no. 09/792,335 \_\_\_\_\_ entitled "Chips With Elevated Sample Surfaces" by Pierre F. Indermuhle et al. (~~Attorney Docket No. 020144-000810~~), which is herein incorporated by reference in its entirety for all purposes.--